

# 20V N-Channel Trench MOSFET

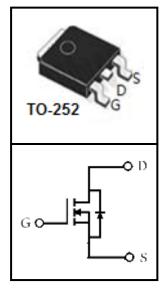
#### **FEATURES**

- Super Low Gate Charge
- 100% EAS Guaranteed
- RoHS compliant
- Green Device Available
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

#### **APPLICATIONS**

- Load Switching
- Hard switched and high frequence circuits
- Uninterruptible power supply





Device Marking and Package Information			
Device	Package	Marking	
CTD02N4P8	TO-252	CTD02N4P8	

Absolute Maximum Ratings at T <sub>j</sub> = 25°C unless otherwise noted				
Parameter		Symbol	Value	Unit
Drain-Source Voltage (V <sub>GS</sub> = 0V)		V <sub>DSS</sub>	20	V
Continuous Drain Current T <sub>C</sub> = 25°C	(note1)		80	А
Continuous Drain Current T <sub>C</sub> = 100°C	(note1)	I <sub>D</sub>	57	А
Pulsed Drain Current	(note2)	I <sub>DM</sub>	320	А
Gate Source Voltage		$V_{GSS}$	±12	V
Single Pulse Avalanche Energy	(note3)	E <sub>AS</sub>	6.5	mJ
Power Dissipation T <sub>C</sub> = 25°C	(note4)	$P_{D}$	87	W
Operating Junction and Storage Temperature Range		$T_J, T_{stg}$	-55~+175	°C

Thermal Characteristics					
Parameter		Symbol	Value	Unit	
Thermal Resistance, Junction-Case	(note1)	$R_{ heta JC}$	2.3	°C/W	
Thermal Resistance Junction-Ambient 1 (t≤10s)	(note1)	$R_{ hetaJA}$	62	°C/W	



Electrical Characteristics T <sub>j</sub> = 25°C unless otherwise specified							
Para mada a			Value				
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	20			V	
7 0 1 1/1 5 1 2		$V_{DS} = 20V, V_{GS} = 0V, T_{J} = 25^{\circ}C$			1	uA	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 20V, V_{GS} = 0V, T_{J} = 100^{\circ}C$			5	uA	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{GS} = \pm 12V$			±100	nA	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	0.5	0.75	1	V	
	R <sub>DS(on)</sub>	$V_{GS} = 4.5V, I_{D} = 30A$		3.1	4.8	mΩ	
Drain-Source On-Resistance (note2)		V <sub>GS</sub> 2.5V, I <sub>D</sub> = 24A		3.8	7.5	mΩ	
Dynamic							
Input Capacitance	C <sub>iss</sub>	$V_{GS} = 0V$ ,		2823		pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS} = 15V$ ,		383			
Reverse Transfer Capacitance	C <sub>rss</sub>	f = 1.0MHz		335			
Total Gate Charge (4.5V)	$Q_g$			39		nC	
Gate-Source Charge	$Q_{gs}$	$V_{DD} = 10V, I_{D} = 40A,$ $V_{GS} = 4.5V$		5.2			
Gate-Drain Charge	$Q_{gd}$	163		14			
Turn-on Delay Time	t <sub>d(on)</sub>			32		ns	
Turn-on Rise Time	t <sub>r</sub>	$V_{DS} = 10V, V_{GS} = 4.5V,$		4			
Turn-off Delay Time	t <sub>d(off)</sub>	$R_G = 3.5\Omega$		124			
Turn-off Fall Time	t <sub>f</sub>			41			
Body Diode Characteristics							
Continuous Body Diode Current	I <sub>S</sub>	T 05.00			80	^	
Pulsed Diode Forward Current	I <sub>SM</sub>	T <sub>C</sub> = 25 °C			320	A	
Body Diode Voltage	V <sub>SD</sub>	$T_J = 25^{\circ}C$ , $I_{SD} = 40A$ , $V_{GS} = 0V$	0.4		1	V	

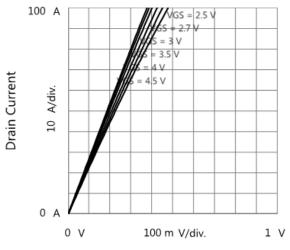
#### **Notes**

- 1. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.
- 2. The data tested by pulsed , pulse width≦300us , duty cycle≦2%
- 3. The EAS data shows Max. rating . The test condition is VDD =20V,VGS =10V,L=0.5mH  $\,$
- 4. The power dissipation is limited by 175°C junction temperature
- 5. The data is theoretically the same as ID and IDM, in real applications, should be limited by total power dissipation.

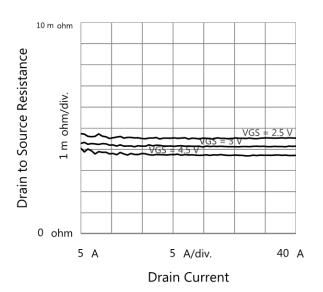


### **Typical Characteristics** $T_1 = 25^{\circ}$ C, unless otherwise noted

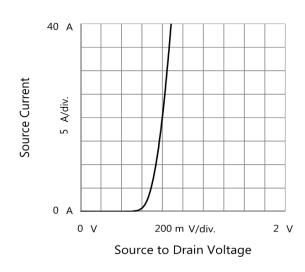
#### **Output Characteristics**



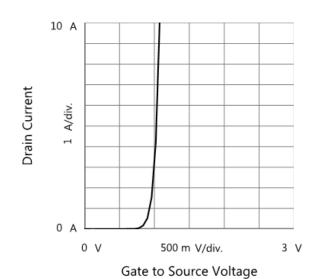
Drain to Source Voltage
Drain to Source Resistance vs. Drain Current



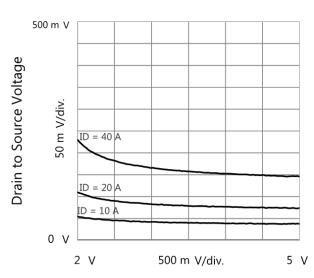
**Body Diode Forward Characteristics** 



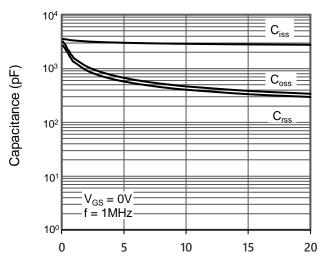
#### Transfer Characteristics



Drain to Source Voltage vs. Gate to Source Voltage



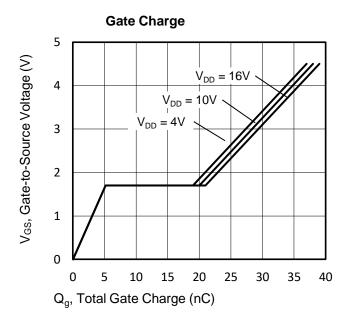
Gate to Source Voltage



V<sub>DS</sub>, Drain-to-Source Voltage (V)



## **Typical Characteristics** $T_J = 25^{\circ}C$ , unless otherwise noted



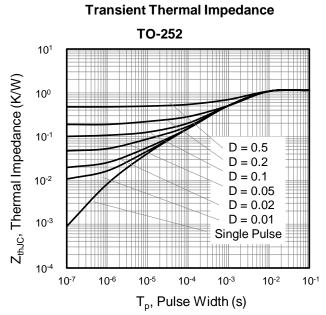




Figure A: Gate Charge Test Circuit and Waveform

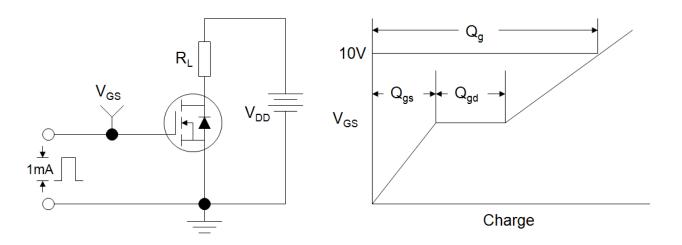


Figure B: Resistive Switching Test Circuit and Waveform

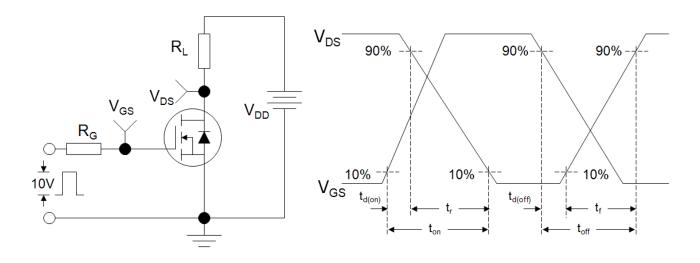
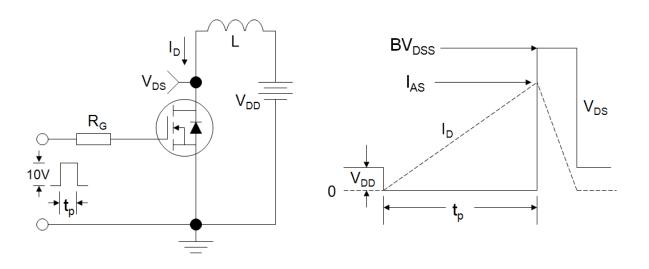
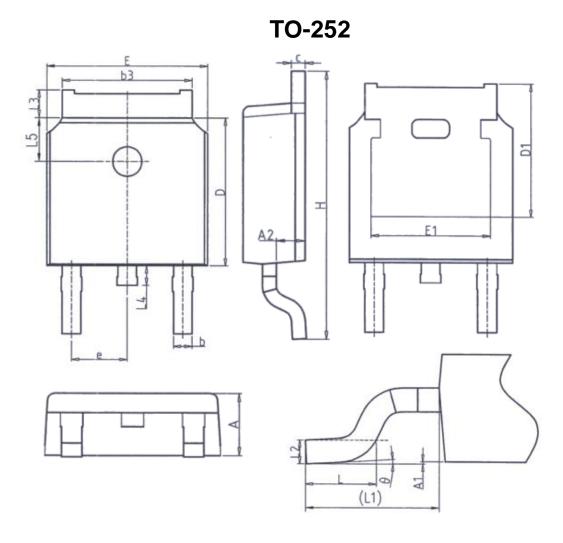


Figure C: Unclamped Inductive Switching Test Circuit and Waveform







Unit: mm				
Symbol	Min.	Max.		
Α	2. 20	2. 40		
A1	0.00	0. 20		
A2	0. 97	1. 17		
b	0. 68	0. 90		
b3	5. 20	5. 50		
С	0. 43	0. 63		
D	5. 98	6. 22		
D1	5. 30REF			
E	6. 40	6. 80		
E1	4. 63	_		

Unit: mm				
Symbol	Min. Max.			
е	2. 286BSC			
Н	9. 40	10.50		
L	1. 38	1. 75		
L1	2. 90REF			
L2	0. 51BSC			
L3	0.88	1. 28		
L4	_	1.00		
L5	1. 65	1. 95		
θ	0°	8°		



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